

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

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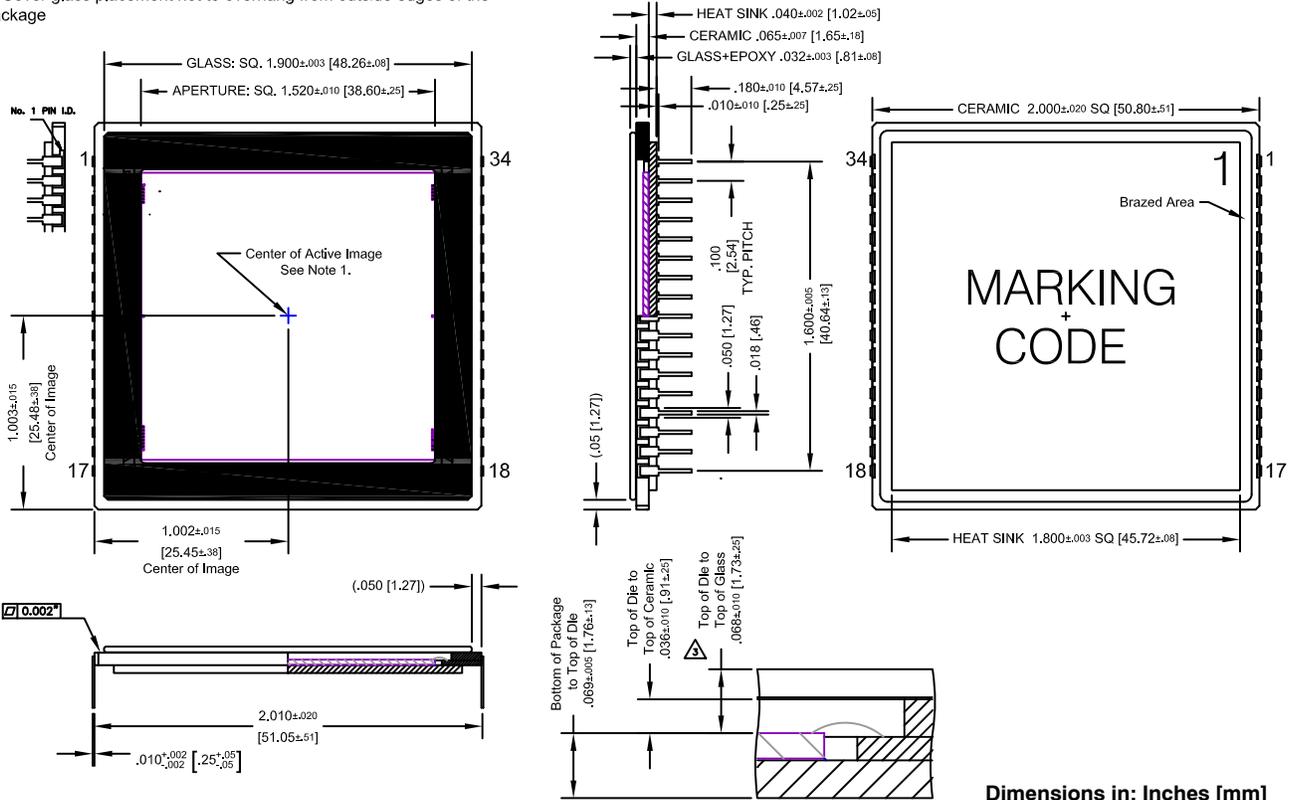
## CERAMIC DIP 34, 50.8x50.8 CASE 125BK ISSUE O

DATE 03 JUL 2014

**NOTES:**

- Center of Active Image is at (+.046, +.078)mm with respect to Center of Package at (0,0).
- Die is visually aligned within 1 degree of any package cavity edge.
- Cover glass placement not to overhang from outside edges of the package

SHOWN WITH SEALED COVER GLASS



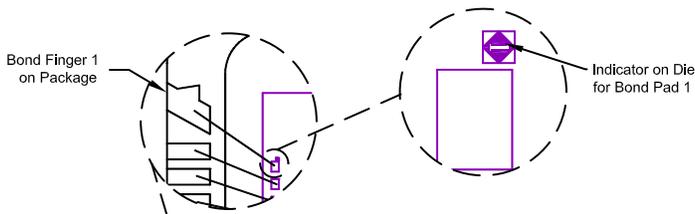
Dimensions in: Inches [mm]

<b>DOCUMENT NUMBER:</b>	<b>98AON87293F</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>CERAMIC DIP 34, 50.8x50.8</b>	<b>PAGE 1 OF 2</b>

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**CASE 125BK**  
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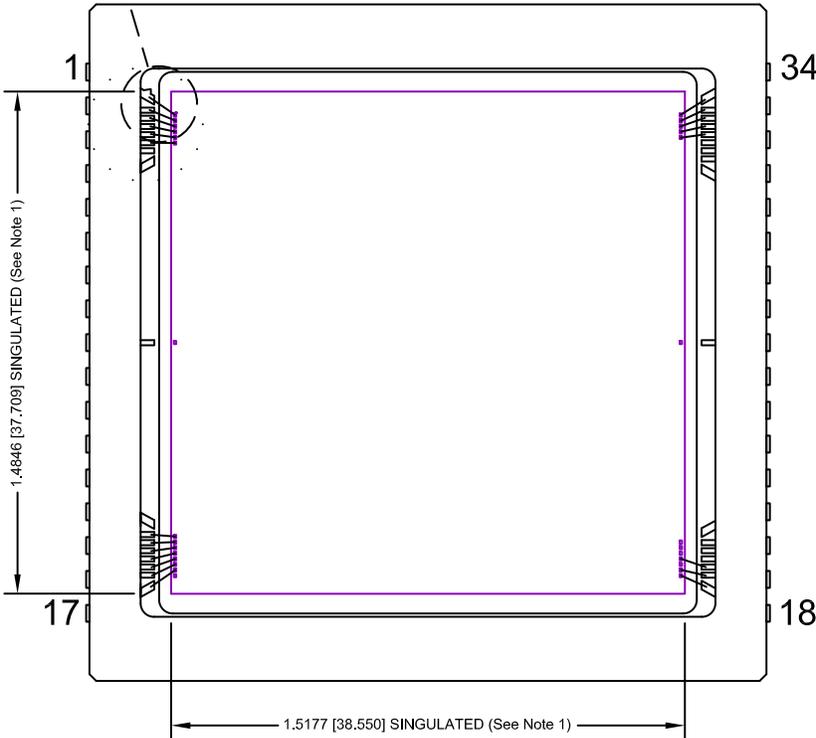


**NOTES:**

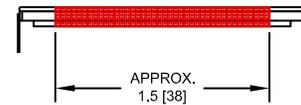
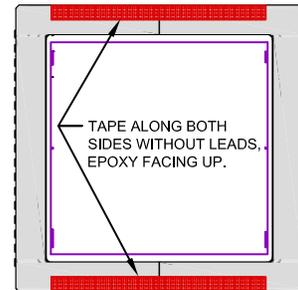
1. SINGULATION ASSUMES 50 MICRON KERF.  
 STEPPED DIE DIMENSION ON WAFER FOR DICING  
 PURPOSES IS 38.60 mm X 37.76 mm.

2 APPLY TAPE TO TWO SIDES AS SHOWN (ASSY # 20304846)

SHOWN WITH NO COVER GLASS



2 SHOWN WITH  
 TAPED ON COVER GLASS



**Dimensions in: Inches [mm]**

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<b>DESCRIPTION:</b>	<b>CERAMIC DIP 34, 50.8x50.8</b>	<b>PAGE 2 OF 2</b>

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